Heraeus

Electronics

PD 205 A-Jet

SMT Adhesive

Description

PD 205 A-Jet is a thermosetting single component, solvent-free polymer adhesive, developed especially for the surface mount of SMT components onto PCBs and for use on bare substrates. This rheology is specially adapted for Jet dispensing

Key Features

- Very wide processing window, no tendency towards stringing
- Rheology is especially developed for Jet dispensing
- High reliability

This picture does not show the packaging of PD205A-Jet and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Physical Properties	
Processing time at 20 – 30°C (days)	Max. 2
Curing Profile	The standard curing conditions are 125°C / 3 minutes. As long as the curing profile is respected, the adhesive can withstand reflow conditions according IPC/JEDEC J-STD-020 1 min / 180 °C 1,5 min / 150 °C 3 min / 125 °C 8 min / 100 °C
Color	Red
Applications	Dispensing Jetting

The descriptions and engineering data shown here have been compiled by Heraeus using commonly-accepted procedures, in conjunction with modern testing equipment, and have been compiled as according to the latest factual knowledge in our possession. The information was up-to date on the date this document was printed (latest versions can always be supplied upon request). Although the data is considered accurate, we cannot guarantee accuracy, the results obtained from its use, or any patent infringement resulting from its use (unless this is contractually and explicitly agreed in writing, in advance). The data is supplied on the condition that the user shall conduct tests to determine materials suitability for particular application. The Heraeus logo, Heraeus, Welco™, Microbond® and mAgic®, and the Welco, Microbond and mAgic figurative mark are trademarks or registered trademarks of Heraeus Holding GmbH or its affiliates. All rights reserved.

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Adhesive Conditioning

- Remove adhesive from fridge: Before opening the package leave it for at least 2 hours at room temperature so that adhesive heats up
- Do not open jar/cartridge while adhesive is cold to prevent condensation
- Before using adhesive cartridge: Before inserting nozzle, press small quantity of glue out of cartridge until homogeneous glue comes out – during storage of cartridges, low viscosity glue constituents may be found on the tip of the cartridge

Cleaning Instructions

Before curing: The adhesive can be removed with Zestron HC and other Zestron and Vigon cleaning materials. Do not use alcohol as this will cure the adhesive. Cleaned dispensing units should be completely dried before installation.

After Curing: Defective components can be replaced by heating (with hot air) the cured adhesive joint above 100 °C. After removing the component (torsion movement), the hot air should be focused on the remaining adhesive in order to remove it with a sharp tool.

Storage Conditions

- Store the SMT-adhesive in originally sealed containers and avoid exposure to high humidity and sunlight
- Store cartridges with tip pointing downwards
- Max. expiration date: Shelf life: Please refer to the expiry date on the label of the packaged product
- Storage condition in the refrigerator at 2 – 10 °C

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